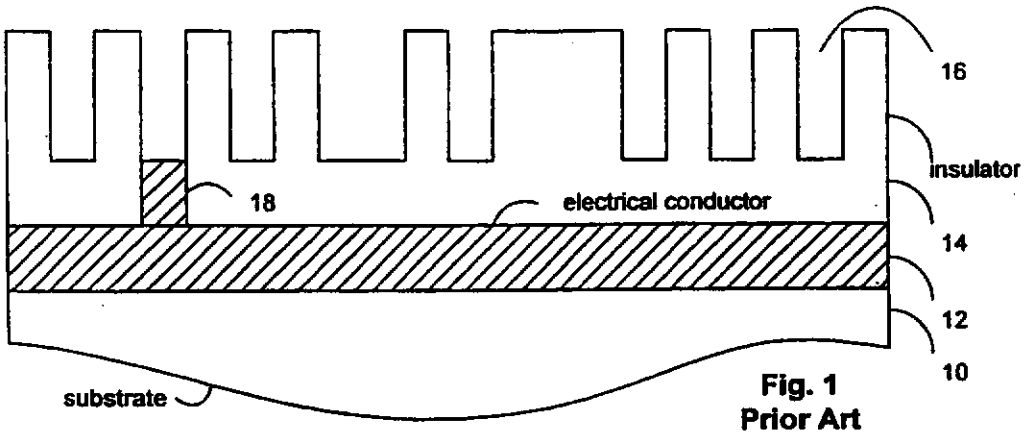


Fig. 1
Prior Art

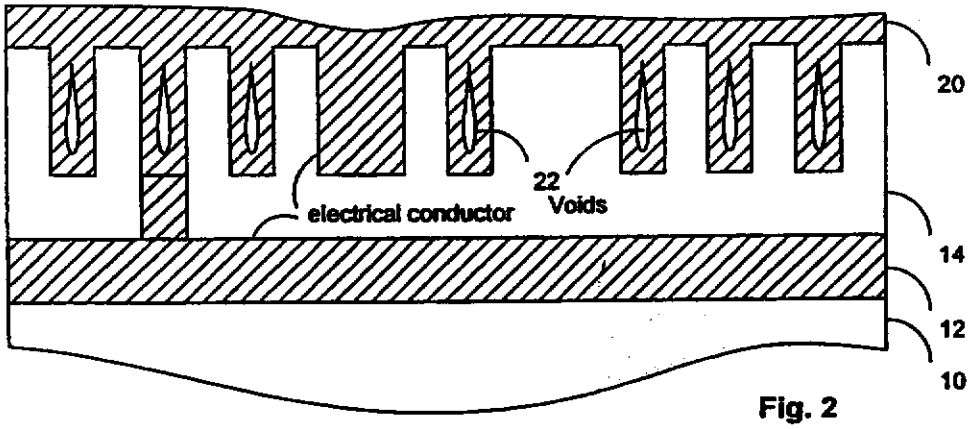


Fig. 2
Prior Art

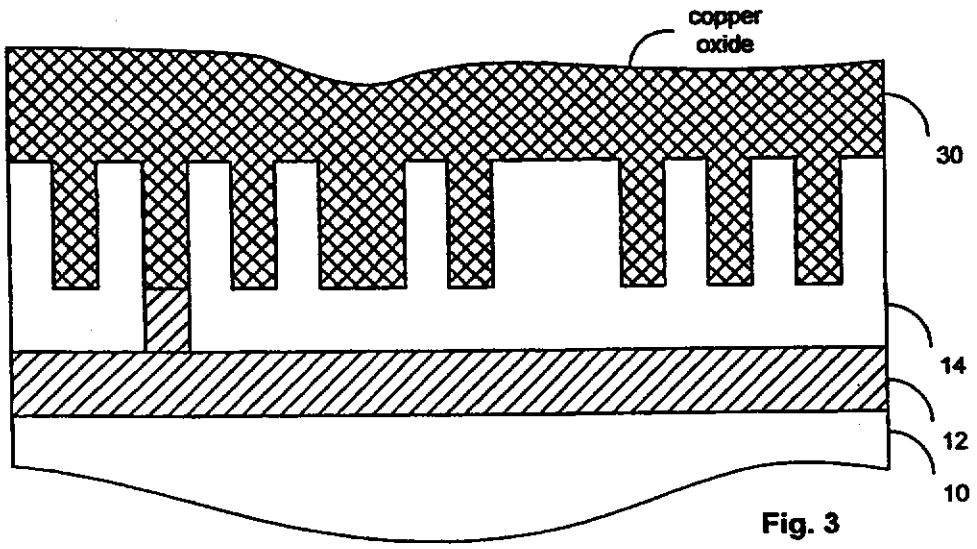


Fig. 3

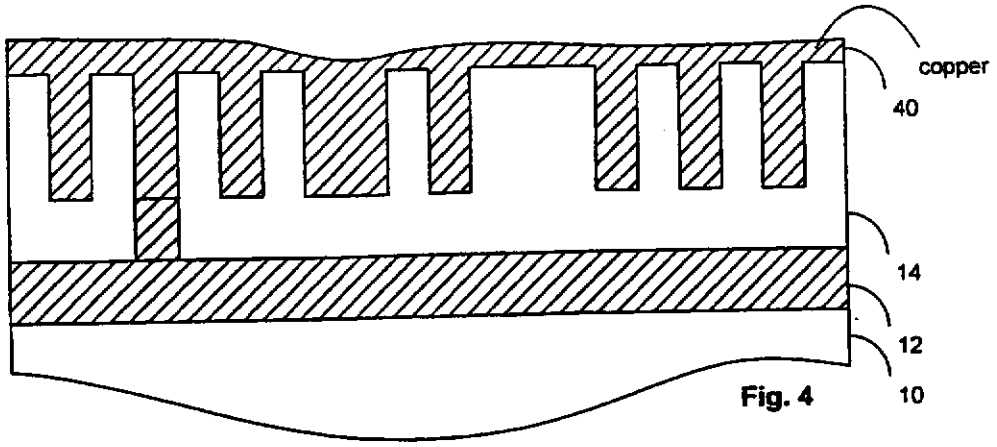


Fig. 4

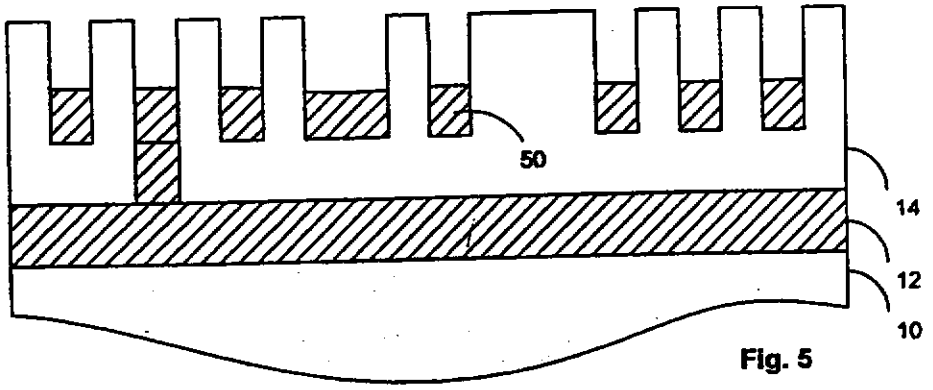


Fig. 5

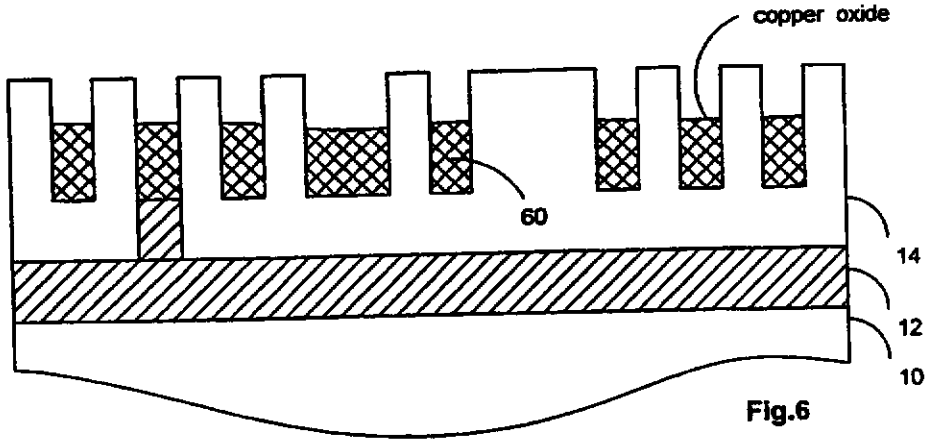


Fig.6

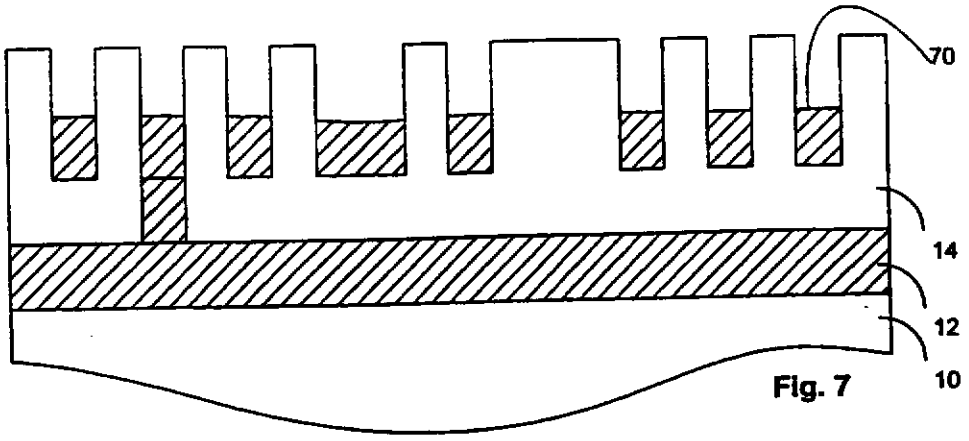


Fig. 7

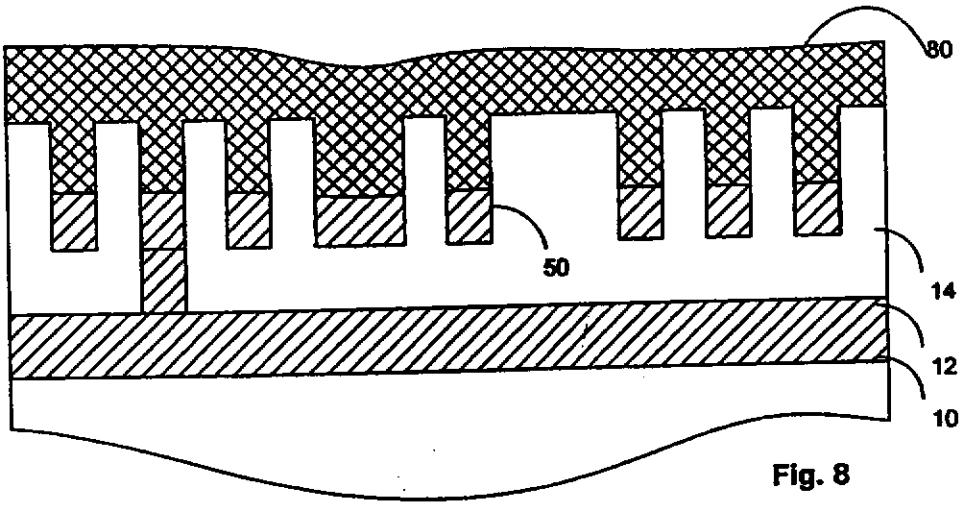


Fig. 8

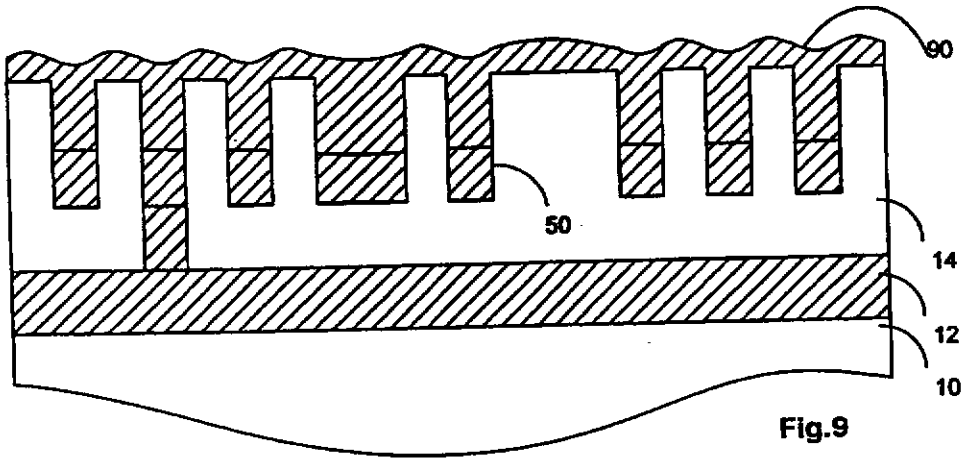


Fig.9

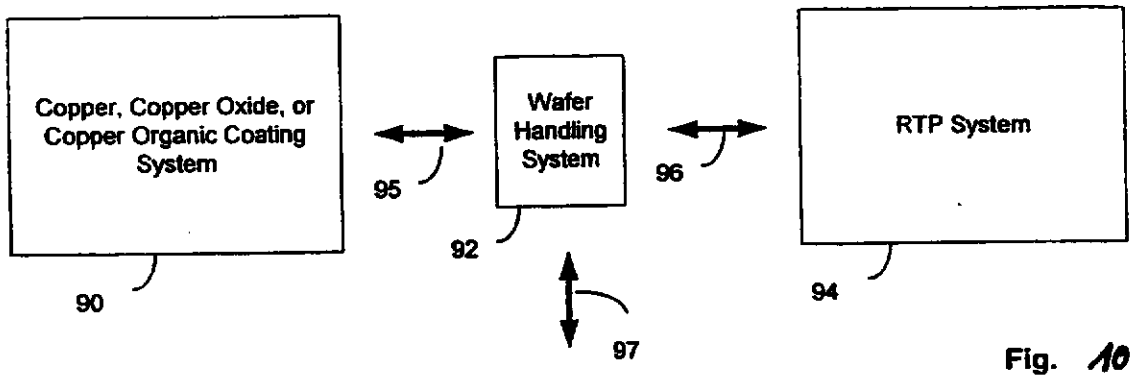

Copper, Copper Oxide, or Copper Organic Coating System
90
95
Wafer Handling System
92
96
RTP System
94
97

Fig. 10

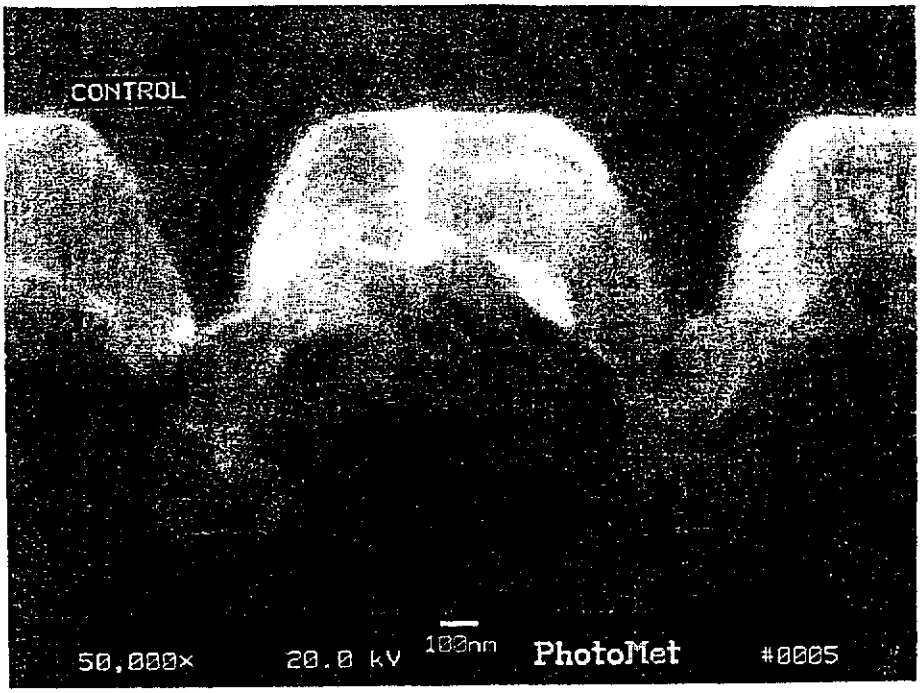

CONTROL
50,000×
20.0 kV
100nm
PhotoMet
#0005

Fig. 11

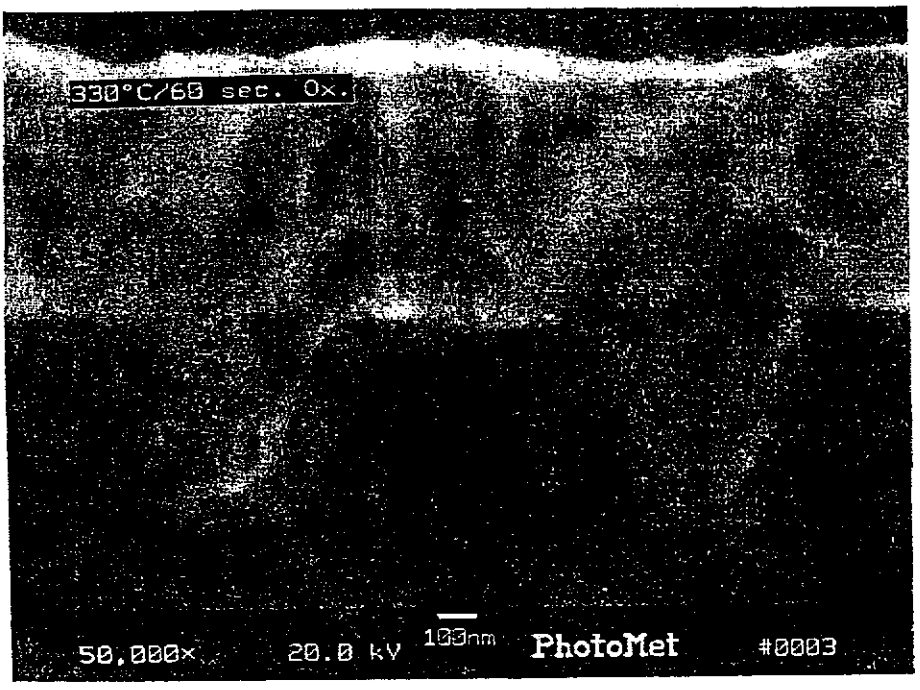

330°C/60 sec. Ox.
50,000×
20.0 kV
100nm
PhotoMet
#0003

Fig. 12

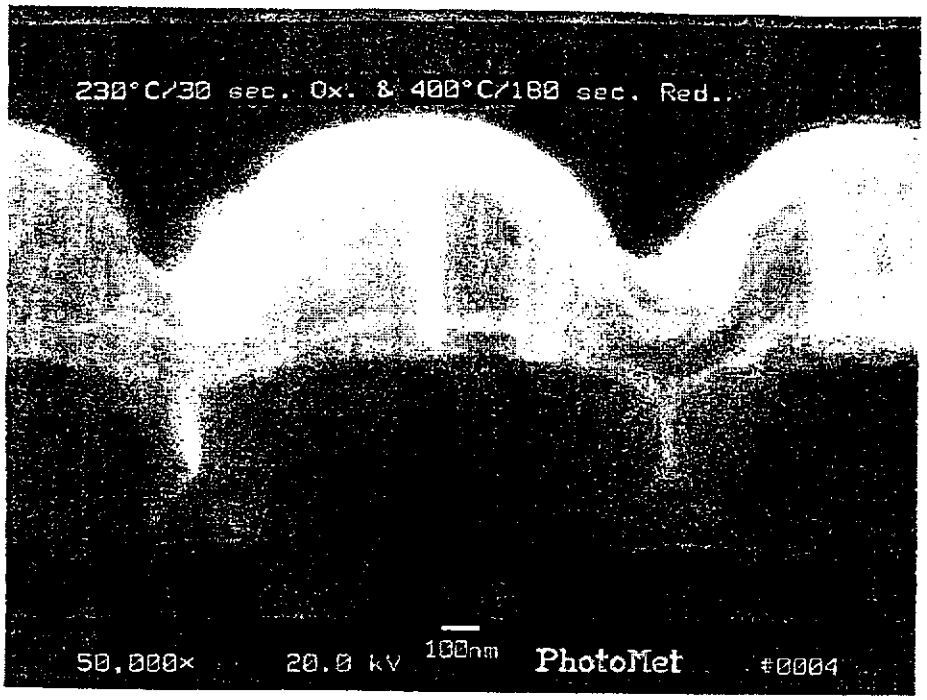

230°C/30 sec. Ox. & 400°C/180 sec. Red..
50,000×
20.0 kV
100nm
PhotoMet
#0004

Fig. 13

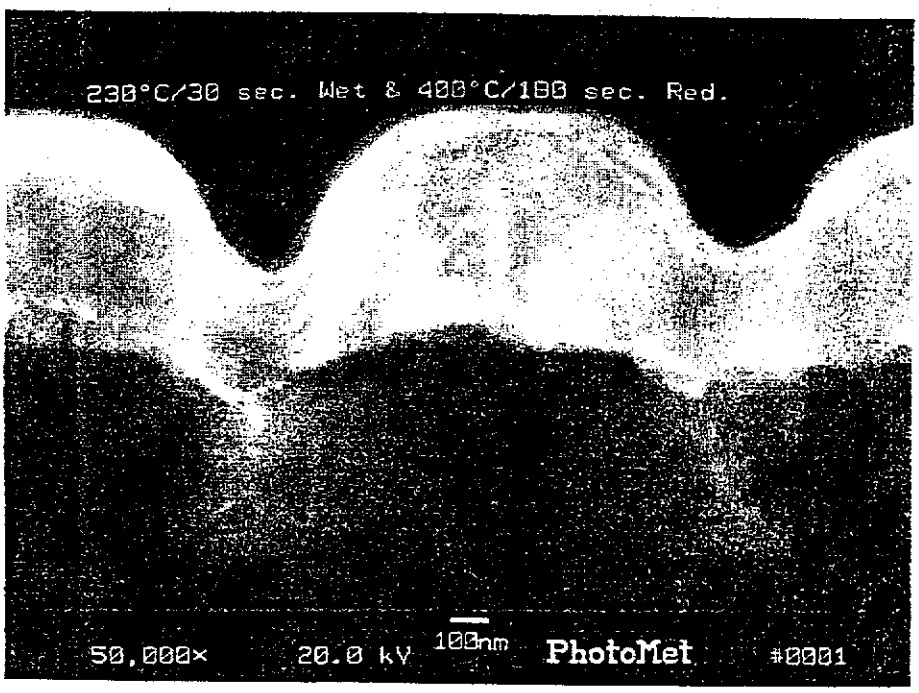

230°C/30 sec. Wet & 400°C/180 sec. Red.
50,000×
20.0 kV
100nm
PhotoMet
#0001

Fig. 14